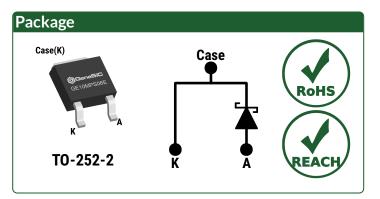
Silicon Carbide Schottky Diode



 V_{RRM} 650 V $I_{F(T_C = 159^{\circ}C)} =$ 10 A 25 nC Qc

Features

- Revolutionary Low Built-In Voltage (VBI)
- Gen5 Thin Chip Technology for Low V_F
- Superior Figure of Merit Qc * VF
- Enhanced Surge Current Robustness Low Thermal Resistance
- Zero Reverse Recovery
- 100% Avalanche (UIL) Tested
- Excellent dV/dt Ruggedness



Advantages

- Low Conduction Losses for All Load Conditions
- Optimal Price Performance
- Increased System Power Density
- High System Reliability
- Reduced Cooling Requirements
- Temperature Independent Fast Switching
- Easy to Parallel without Thermal Runaway

Applications

- Switched Mode Power Supply (SMPS)
- Solar Inverter
- Server and Telecom Power Supply
- **Battery Charger**
- Uninterruptible Power Supply (UPS)
- Motor Control
- Power Factor Correction (PFC)

Parameter	Symbol	Conditions Values		Unit	Note
Repetitive Peak Reverse Voltage	V_{RRM}		650	٧	
Continuous Forward Current	l _F	T _C = 100°C, D = 1	23		
		$T_C = 135^{\circ}C$, D = 1	17	Α	Fig. 4
		$T_C = 159^{\circ}C$, D = 1	10		
Non-Repetitive Peak Forward Surge Current, Half Sine Wave	I F,SM	T_C = 25°C, t_P = 10 ms	70	А	
		T_C = 150°C, t_P = 10 ms	56		
Repetitive Peak Forward Surge Current, Half Sine Wave	I _{F,RM}	T_C = 25°C, t_P = 10 ms	42	Α	
		T_C = 150°C, t_P = 10 ms	29		
Non-Repetitive Peak Forward Surge Current	I _{F,MAX}	T _C = 25°C, t _P = 10 μs	350	Α	
i ² t Value	∫i²dt	T_C = 25°C, t_P = 10 ms	24	A ² s	
Non-Repetitive Avalanche Energy	E _{AS}	L = 2.6 mH, I _{AS} = 10 A	131	mJ	
Diode Ruggedness	dV/dt	V _R = 0 ~ 520 V	200	V/ns	
Power Dissipation	P _{TOT}	T _C = 25°C	157	W	Fig. 3
Operating and Storage Temperature	Tj, Tstg		-55 to 175	°C	

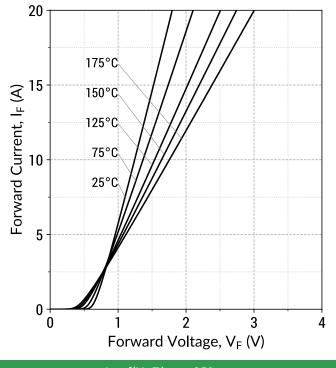


Electrical Characteristics Values **Parameter Symbol Conditions** Unit Note Min. Typ. Max. $I_F = 10 A$, $T_i = 25$ °C 1.25 1.4 ٧ Diode Forward Voltage V_{F} Fig. 1 $I_F = 10 A, T_j = 175$ °C 1.75 $V_R = 650 \text{ V, } T_i = 25^{\circ}\text{C}$ 1 10 **Reverse Current** Fig. 2 I_R μΑ $V_R = 650 \text{ V, } T_i = 175^{\circ}\text{C}$ 194 $V_R = 200 V$ 17 **Total Capacitive Charge** $Q_{\mathbb{C}}$ nC Fig. 7 $V_R = 400 V$ 25 $I_F \leq I_{F,MAX}$ $dI_F/dt = 200 A/\mu s$ $V_R = 200 V$ Switching Time < 10 ts ns $V_R = 400 V$ $V_R = 1 V$, f = 1MHz466 С **Total Capacitance** рF Fig. 6 V_R = 400 V, f = 1MHz 33

Thermal/Package Characteristics										
Symbol	Conditions	Values			I I mile	Moto				
		Min.	Тур.	Max.	Unit	Note				
RthJC			0.96		°C/W	Fig. 9				
W _T			0.3		g					
	Symbol R _{thJC}	Symbol Conditions R _{thJC}	Symbol Conditions Min.	$\begin{tabular}{c} Symbol & Conditions & \hline & Values \\ \hline Min. & Typ. \\ R_{thJC} & 0.96 \\ \hline \end{tabular}$	Symbol Conditions Values Min. Typ. Max.	$\begin{tabular}{l lllllllllllllllllllllllllllllllllll$				

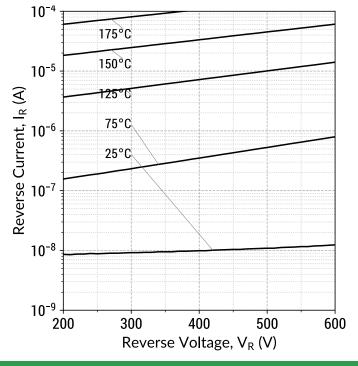






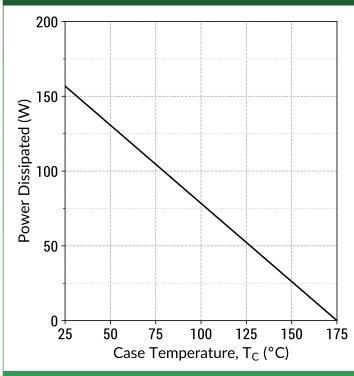
 $I_F = f(V_F, T_j); t_P = 250 \ \mu s$

Figure 2: Typical Reverse Characteristics



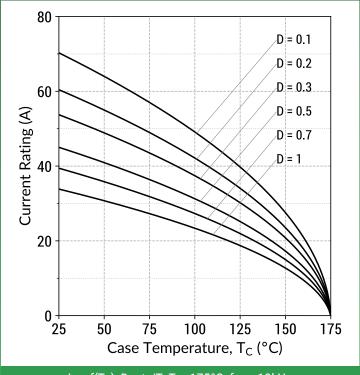
 $I_R = f(V_R, T_j)$

Figure 3: Power Derating Curves



 $P_{TOT} = f(T_C); T_j = 175^{\circ}C$

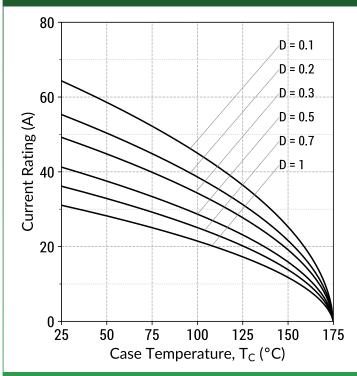
Figure 4: Current Derating Curves (Typical V_F)



 $I_F = f(T_C)$; D = t_P/T ; $T_j \le 175$ °C; $f_{SW} > 10$ kHz

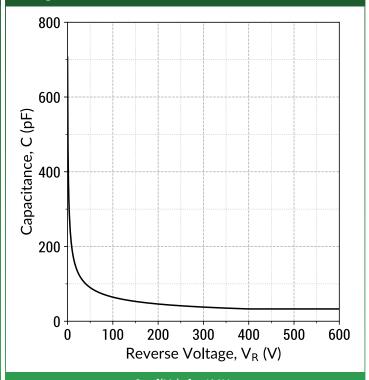


Figure 5: Current Derating Curves (Maximum V_F)



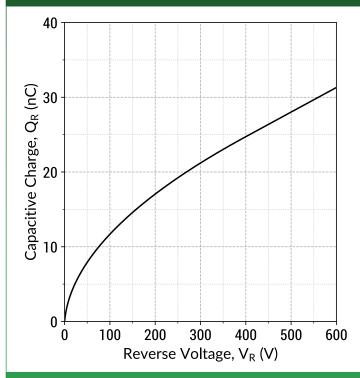
 $I_F = f(T_C)$; D = t_P/T ; $T_j \le 175$ °C; $f_{SW} > 10$ kHz

Figure 6: Typical Junction Capacitance vs Reverse Voltage Characteristics



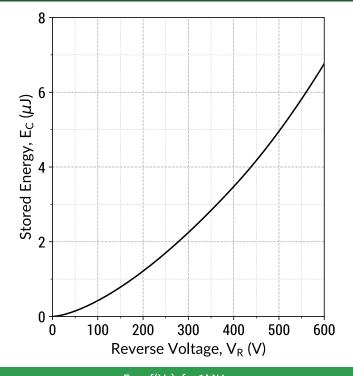
 $C = f(V_R)$; f = 1MHz

Figure 7: Typical Capacitive Charge vs Reverse Voltage Characteristics



 $Q_C = f(V_R)$; f = 1MHz

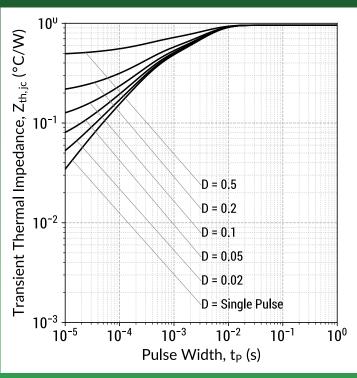
Figure 8: Typical Capacitive Energy vs Reverse Voltage Characteristics



 $E_C = f(V_R)$; f = 1MHz

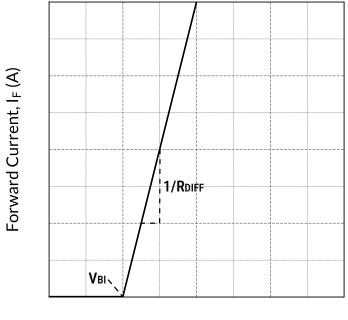


Figure 9: Transient Thermal Impedance



 $Z_{th,jc} = f(t_P,D); D = t_P/T$

Figure 10: Forward Curve Model



Forward Voltage, V_F (V)

 $I_F = f(V_F, T_j)$

Forward Curve Model Equation:

 $I_F = (V_F - V_{BI})/R_{DIFF} (A)$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m \times T_j + n (V)$$

 $m = -0.00124 (V/^{\circ}C)$
 $n = 0.72 (V)$

Differential Resistance (RDIFF):

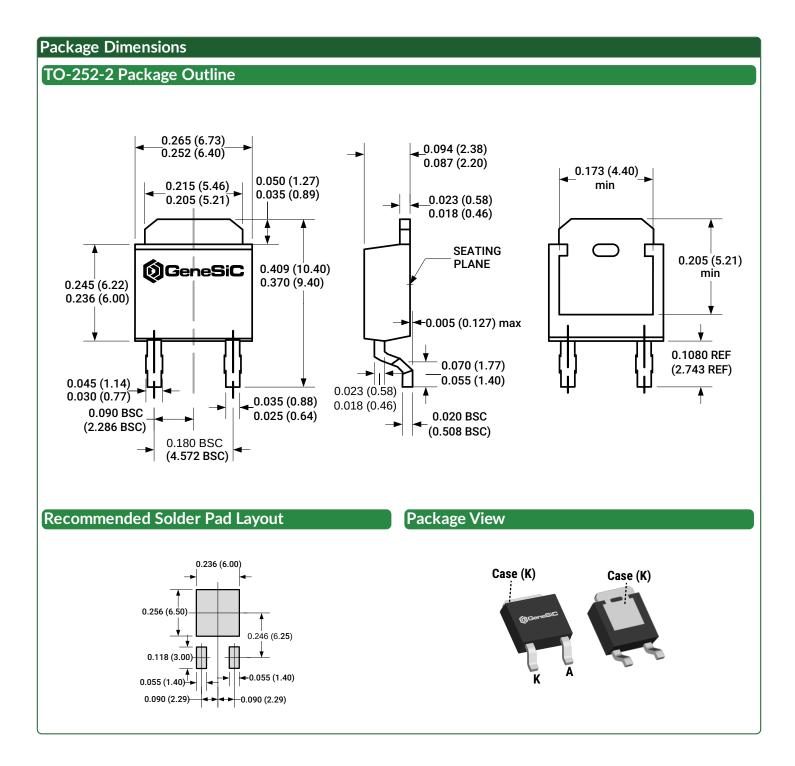
$$R_{DIFF}(T_j) = a \times T_j^2 + b \times T_j + c (\Omega)$$

 $a = 9.62e-07 (\Omega/^{\circ}C^2)$
 $b = 0.000272 (\Omega/^{\circ}C)$
 $c = 0.0481 (\Omega)$

Forward Power Loss Equation:

$$P_{LOSS} = V_{BI}(T_j) \times I_{AVG} + R_{DIFF}(T_j) \times I_{RMS}^2$$





NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS.





Compliance

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

REACH Compliance

REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

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Revision History

Rev 21/Jun: Updated with most recent test data

Supersedes: Rev 20/Jul



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